



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-07-10
Contact Name *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Authorized Representative *	Rossana Bonaccorso
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STTH30RQ06G2Y-TR	AT(9*U65Q2AI	A	3068	2018-07-10
	Amount	UoM	Unit type	ST ECOPACK Grade
	1380.00	mg	Each	ECOPACK1
	Comment	ECOPACK® or ECOPACK® 1 is STMicroelectronics trade name for ROHS compliant devices		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2-7.2-4.5	3	GULL WING	
Comment	H2PAK HC 2-3 Leads			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 25th May 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.28	Die - Leadframe	199
Lead	8.04	Soft solder	5827
Antimony trioxide	6.09	Mold compound	4413

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	AT(9*U65Q2AI					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	7.869	mg	supplier	die	Silicon (Si)	7440-21-3		7.540	mg	958203	5464
				supplier	metallization	Aluminium (Al)	7429-90-5		0.112	mg	14233	81
				supplier	Passivation	Silicon Oxide	7631-86-9		0.037	mg	4702	27
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.004	mg	508	3
				supplier	back side metallization	Gold (Au)	7440-57-5		0.013	mg	1652	9
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.061	mg	7752	44
Leadframe	M-004 Copper and its alloys	848.009	mg	supplier	polymer die coating	Probimide	Proprietary		0.102	mg	12950	74
				supplier	alloy	Copper (Cu)	7440-50-8		846.676	mg	998428	613533
				supplier	alloy	Iron (Fe)	7439-89-6		0.848	mg	1000	614
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.254	mg	300	184
				supplier	metallization	Nickel (Ni)	7440-02-0		0.214	mg	252	155
				supplier	metallization	Phosphorus (P)	7723-14-0		0.017	mg	20	12
Soft solder	Solder	8.420	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	8.041	mg	954988	5827
				supplier	solder	Silver (Ag)	7440-22-4		0.211	mg	25059	153
				supplier	solder	Tin (Sn)	7440-31-5		0.168	mg	19953	122
Bonding wires	M-011 Other inorganic materials	4.925	mg	supplier	wire	Aluminium (Al)	7429-90-5		4.925	mg	1000000	3569
Encapsulation	M-011 Other inorganic materials	507.043	mg	supplier	mold compound	Silica, vitreous	60676-86-0		408.676	mg	805999	296142
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		35.493	mg	70000	25720
				supplier	mold compound	Phenol resin	9003-35-4		20.282	mg	40001	14697
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		30.423	mg	60001	22046
				supplier	mold compound	Antimony Trioxide	1309-64-4		6.085	mg	12000	4409
				supplier	mold compound	Brominated Epoxy Resin	40039-93-8		3.549	mg	6999	2572
Connections coating	Solder	3.734	mg	supplier	mold compound	Carbon black	1333-86-4		2.535	mg	5000	1837
				supplier	solder alloy	Tin (Sn)	7440-31-5		3.734	mg	1000000	2706